

Schottky Power Rectifier, Switch-Mode, 10 A, 45 V

MBRB1045G, MBRD1045G, SBRB1045G, SBRD81045T4G

This series of Power Rectifiers employs the Schottky Barrier principle in a large metal-to-silicon power diode. State-of-the-art geometry features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for use in low voltage, high frequency switching power supplies, free wheeling diodes, and polarity protection diodes.

Features

- Guardring for Stress Protection
- Low Forward Voltage
- 175°C Operating Junction Temperature
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Short Heat Sink Tab Manufactured – Not Sheared!
- SBRB and SBRD8 Prefixes for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Mechanical Characteristics:

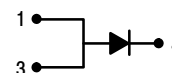
- Case: Epoxy, Molded, Epoxy Meets UL 94 V-0
- Weight: 1.7 grams for D²PAK (approximately)
0.4 grams for DPAK (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Device Meets MSL1 Requirements
- ESD Ratings:
 - ◆ Machine Model = C (> 400 V)
 - ◆ Human Body Model = 3B (> 8000 V)



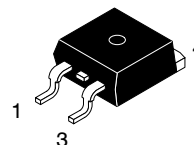
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SCHOTTKY BARRIER RECTIFIER 10 AMPERES, 45 VOLTS



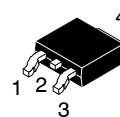
MARKING DIAGRAM



D²PAK-3
CASE 418B

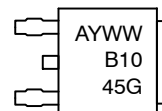


A = Assembly Location
Y = Year
WW = Work Week
MBRB1045 = Device Code
G = Pb-Free Package
AKA = Diode Polarity



DPAK
CASE 369C

MARKING DIAGRAM



A = Assembly Location
Y = Year
WW = Work Week
B1045 = Device Code
G = Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

MBRB1045G, MBRD1045G, SBRB1045G, SBRD81045T4G

MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|--|---------------------------------|---|------------------------|
| Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage | V_{RRM} V_{RWM} V_R | 45 | V |
| Average Rectified Forward Current, $T_C = 135^\circ\text{C}$ | $I_{F(AV)}$ | 10 | A |
| Peak Repetitive Forward Current (Square Wave, Duty = 0.5) $T_C = 135^\circ\text{C}$ | I_{FRM} | 20 | A |
| Nonrepetitive Peak Surge Current (Surge applied at rated load conditions halfwave, single phase, 60 Hz) | I_{FSM} | 150 (MBRB/SBRB) 70 (MBRD/SBRD) | A |
| Operating Junction and Storage Temperature Range (Note 1) | T_J, T_{stg} | -65 to +175 | $^\circ\text{C}$ |
| Voltage Rate of Change (Rated V_R) | dv/dt | 10000 | $\text{V}/\mu\text{s}$ |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. The heat generated must be less than the thermal conductivity from Junction-to-Ambient: $dP_D/dT_J < 1/R_{\theta JA}$.

THERMAL CHARACTERISTICS

| Characteristic | Symbol | Value | Unit |
|---|------------------------------------|------------|---------------------------|
| Thermal Resistance, (MBRB1045G) Junction-to-Case (Note 2) Junction-to-Ambient (Note 2) | $R_{\theta JC}$ $R_{\theta JA}$ | 1.0 50 | $^\circ\text{C}/\text{W}$ |
| (MBRD1045G) Junction-to-Case (Note 2) Junction-to-Ambient (Note 2) | $R_{\theta JC}$ $R_{\theta JA}$ | 2.43 68 | |

2. When mounted using minimum recommended pad size on FR-4 board.

ELECTRICAL CHARACTERISTICS

| Characteristic | Symbol | Value | Unit |
|---|--------|----------------------|------|
| Maximum Instantaneous Forward Voltage (Note 3) ($I_F = 10$ Amps, $T_J = 125^\circ\text{C}$) ($I_F = 20$ Amps, $T_J = 125^\circ\text{C}$) ($I_F = 20$ Amps, $T_J = 25^\circ\text{C}$) | V_F | 0.57 0.72 0.84 | V |
| Maximum Instantaneous Reverse Current (Note 3) (Rated dc Voltage, $T_J = 125^\circ\text{C}$) (Rated dc Voltage, $T_J = 25^\circ\text{C}$) | I_R | 15 0.1 | mA |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Pulse Test: Pulse Width = 300 μs , Duty Cycle $\leq 2.0\%$

ORDERING INFORMATION

| Device | Package | Shipping† |
|---------------|-----------------------------------|---------------------------|
| MBRB1045G | D ² PAK-3 (Pb-Free) | 50 Units / Rail |
| SBRB1045G | | 50 Units / Rail |
| MBRB1045T4G | | 800 Units / Tape & Reel |
| SBRB1045T4G | | 800 Units / Tape & Reel |
| MBRD1045G | DPAK (Pb-Free) | 50 Units / Rail |
| MBRD1045T4G | | 2,500 Units / Tape & Reel |
| SBRD81045T4G | | 2,500 Units / Tape & Reel |
| SSBRD81045T4G | | 2,500 Units / Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MBRB1045G, MBRD1045G, SBRB1045G, SBRD81045T4G

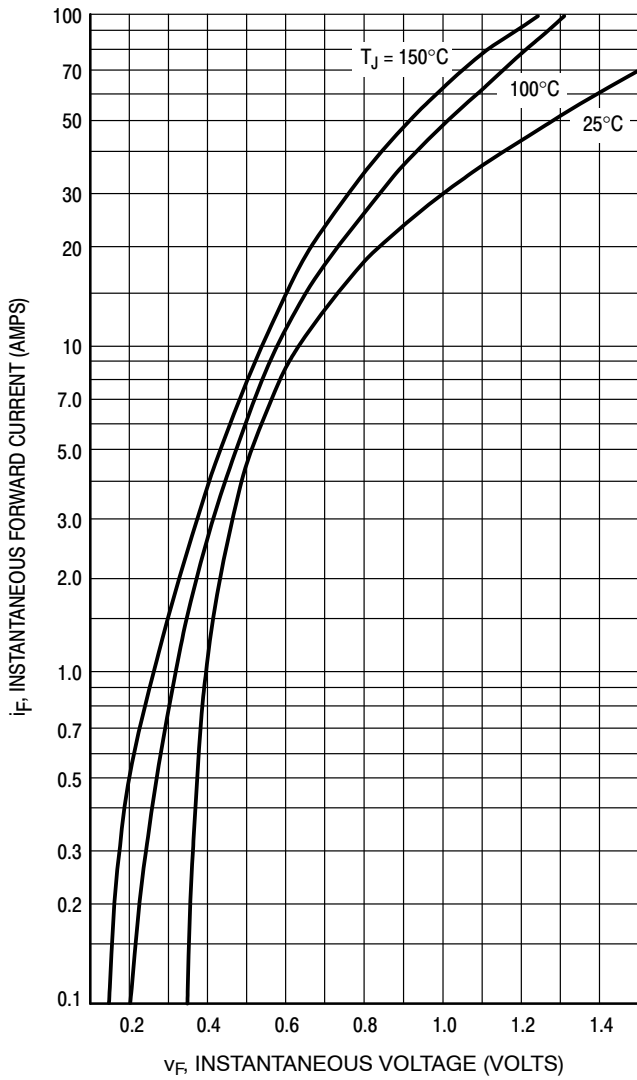


Figure 1. Maximum Forward Voltage

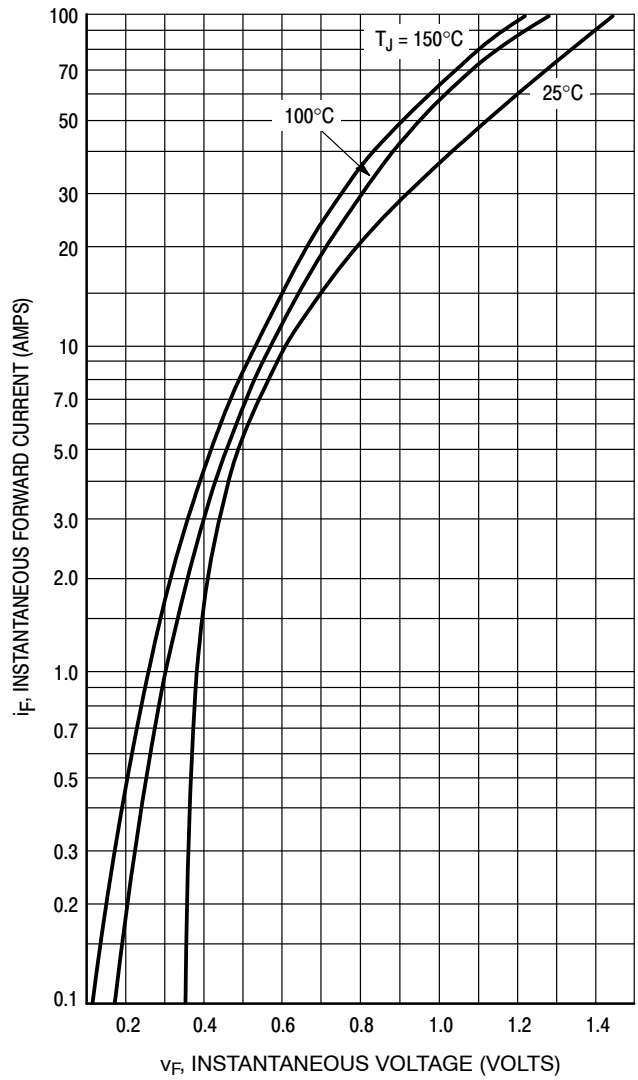


Figure 2. Typical Forward Voltage

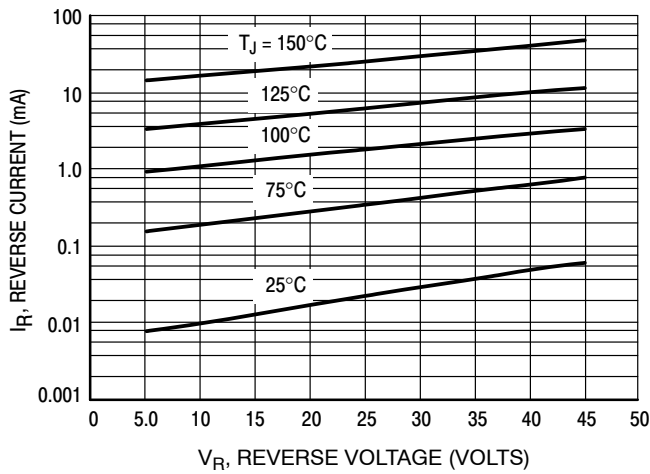


Figure 3. Maximum Reverse Current

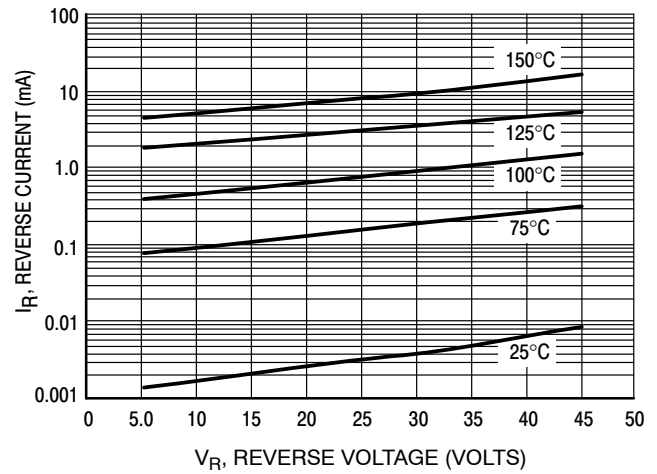


Figure 4. Typical Reverse Current

MBRB1045G, MBRD1045G, SBRB1045G, SBRD81045T4G

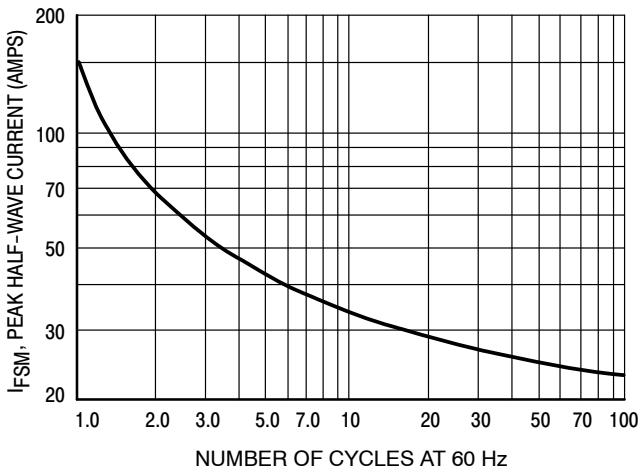


Figure 8. Maximum Surge Capability

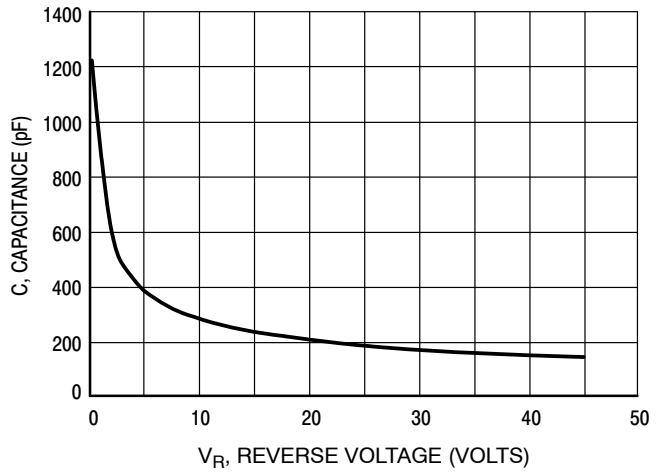
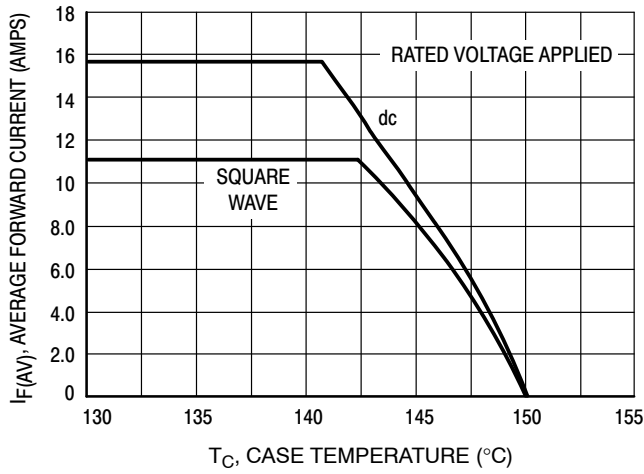


Figure 5. Typical Capacitance



**Figure 6. Current Derating, Case,
 $R_{\theta JC} = 1.0 \text{ } ^\circ\text{C/W}$**

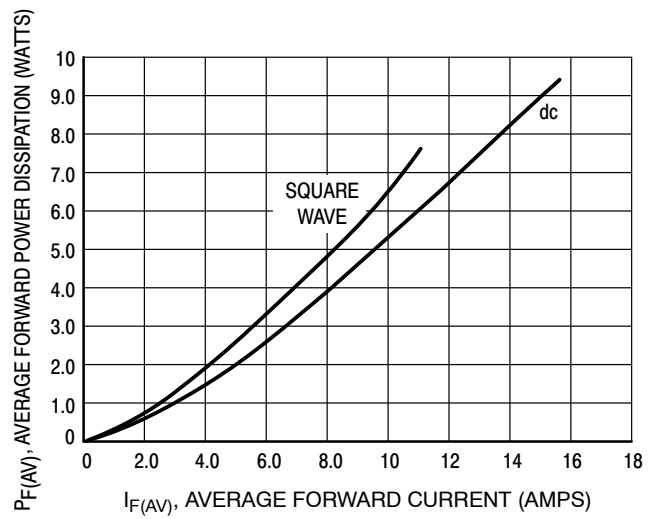


Figure 7. Forward Power Dissipation

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

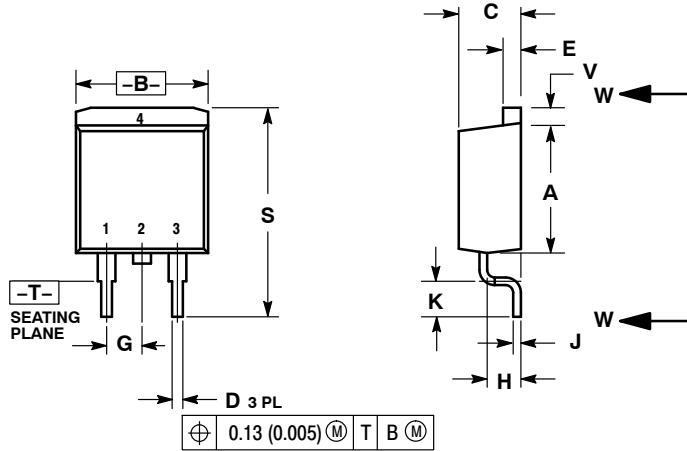
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D²PAK 3
CASE 418B-04
ISSUE L

DATE 17 FEB 2015

SCALE 1:1

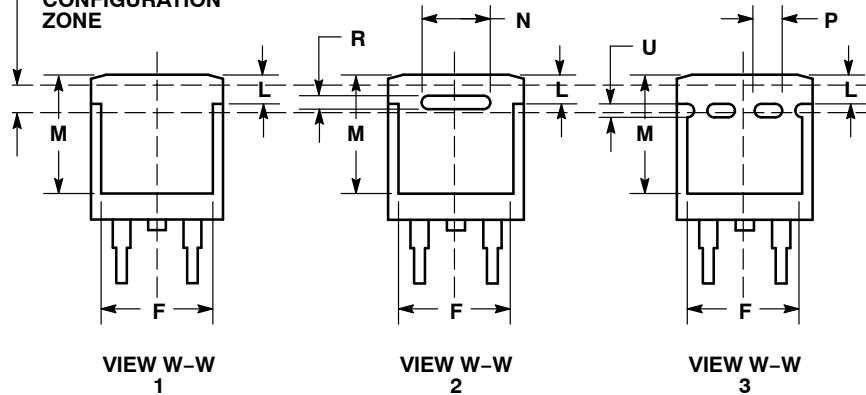


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. 418B-01 THRU 418B-03 OBSOLETE, NEW STANDARD 418B-04.

| DIM | INCHES | | MILLIMETERS | |
|-----|--------|-------|-------------|-------|
| | MIN | MAX | MIN | MAX |
| A | 0.340 | 0.380 | 8.64 | 9.65 |
| B | 0.380 | 0.405 | 9.65 | 10.29 |
| C | 0.160 | 0.190 | 4.06 | 4.83 |
| D | 0.020 | 0.035 | 0.51 | 0.89 |
| E | 0.045 | 0.055 | 1.14 | 1.40 |
| F | 0.310 | 0.350 | 7.87 | 8.89 |
| G | 0.100 | BSC | 2.54 | BSC |
| H | 0.080 | 0.110 | 2.03 | 2.79 |
| J | 0.018 | 0.025 | 0.46 | 0.64 |
| K | 0.090 | 0.110 | 2.29 | 2.79 |
| L | 0.052 | 0.072 | 1.32 | 1.83 |
| M | 0.280 | 0.320 | 7.11 | 8.13 |
| N | 0.197 | REF | 5.00 | REF |
| P | 0.079 | REF | 2.00 | REF |
| R | 0.039 | REF | 0.99 | REF |
| S | 0.575 | 0.625 | 14.60 | 15.88 |
| V | 0.045 | 0.055 | 1.14 | 1.40 |

VARIABLE CONFIGURATION ZONE



- | | | | | | |
|--|---|---|--|---|--|
| STYLE 1: PIN 1. BASE 2. COLLECTOR 3. EMITTER 4. COLLECTOR | STYLE 2: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN | STYLE 3: PIN 1. ANODE 2. CATHODE 3. ANODE 4. CATHODE | STYLE 4: PIN 1. GATE 2. COLLECTOR 3. EMITTER 4. COLLECTOR | STYLE 5: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. ANODE | STYLE 6: PIN 1. NO CONNECT 2. CATHODE 3. ANODE 4. CATHODE |
|--|---|---|--|---|--|

MARKING INFORMATION AND FOOTPRINT ON PAGE 2

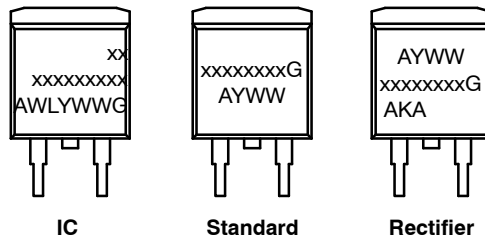
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CASE 418B-04
ISSUE L

DATE 17 FEB 2015

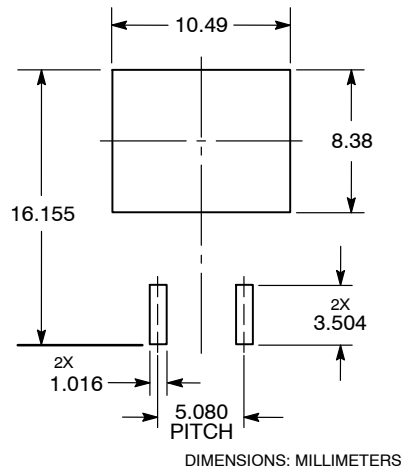
**GENERIC
MARKING DIAGRAM***



- xx = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- Y = Year
- WW = Work Week
- G = Pb-Free Package
- AKA = Polarity Indicator

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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